



## Final Product Change Notification

201710013F01

**Issue Date:** 15-Nov-2017

**Effective Date:** 13-Feb-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



# QUALITY

### Change Category

- |  |   |  |  |   |
|--|---|--|--|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process   | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location           | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input checked="" type="checkbox"/> Test Process | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location  | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment          | <input type="checkbox"/> Electrical spec./Test coverage |

## HC12KA4 Room Test Elimination

### Details of this Change

NXP Semiconductors announces room temperature test elimination from the Final Test production flow for the HC12KA4 associated with this notification. Room test performance is covered by Probe Test and the remaining Final Test production flow.

Current Production Final Test Flow:

ROOM Final Test - HOT Final Test with in-line QA Gate Tests

New Production Final Test Flow:

HOT Final Test with in-line QA Gate Tests

This evaluation has been successfully completed according to NXP specifications.

### Why do we Implement this Change

Qualification of room temperature test elimination for improved capacity and customer supply assurance

### Identification of Affected Products

Product identification does not change

## Product Availability

### Sample Information

Not applicable

### Production

Planned first shipment 01-Apr-2018

## Impact

No change to product form, fit, function, or reliability.

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 15-Dec-2017.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Hairong Zhu

**Position** Product Engineer

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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### Affected Part Number

MC812A4CPVE8